

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Eberhard POTEHPKA
Application No.: 09/668,866
Filed: September 25, 2000
For: APPARATUS FOR REMOVING
SEMICONDUCTOR WAFERS FROM
WITHIN THE RUNNER DISKS OF A
DOUBLE-SIDED POLISHING MACHINE
Examiner: Nguyen, Dung V
Group Art Unit: 3723

Box Patent Application
Assistant Commissioner for Patents
Washington, D.C. 20231

Docket No.: H01.2-9276

AMENDMENT

In response to the Office Action dated December 17, 2001, Applicant amends pending claims 1, 3, and 9, submits new claim 11, and replaces several paragraphs of the specification.

In the Claim:

Please replace claims 1, 3, and 9 with the following amended claims:

1. (Amended) A double-sided polishing machine, comprising:

an upper polishing disk, a lower polishing disk, and runner disks on the lower polishing disk having openings for accommodating wafers, the runner disks being moved between the polishing disks upon rotation of the polishing disks for machining both surfaces of the wafers;

control means adapted to stop the movement of the runner disk such that the runner disks attain a precise predetermined position on the lower polishing disk;

an unloader assembly provided adjacent the polishing machine and said unloader assembly having a single arm member supporting a suction head designed to rotate about a first vertical axis, the suction head being provided with a plurality of suction ports for a